

Title (en)

Process and apparatus for the electrolytic production of a metal foil.

Title (de)

Verfahren und Vorrichtung zur elektrolytischen Herstellung einer Metallfolie.

Title (fr)

Procédé et installation pour la fabrication d'une feuille métallique par dépôt électrique.

Publication

**EP 0369983 B1 19940420 (DE)**

Application

**EP 89890287 A 19891102**

Priority

- AT 226389 A 19890928
- AT 280188 A 19881115

Abstract (en)

[origin: US5009750A] In a process for the manufacture of a metal foil, the metal foil is deposited electrolytically on an endless carrier belt, preferably an endless metal belt, in one or more cells, the current density being set to different levels in the plurality of cells and/or within each individual cell. A post treatment of the metal foil manufactured takes place wholly or at least in part on the endless carrier belt, thereby metal foils, respectively metal composite foils can be manufactured at favorable cost and with low labor input. The apparatus for carrying out the process comprises a plurality, at least two, vertical deposition cells having two upper deflecting rolls 21, 21' and at least one lower deflecting roll 22, the endless carrier belt 1, the anode 23, optionally composed of a plurality of partial anodes, and lateral sealing strips 24, forming a closed shaft through which the electrolyte flows, a plurality of, at least three, current rolls 30, 30', 22 being associated with each cell 2 and the arc of contact being at least 2 DEG .

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**C25D 1/04**; **C25D 7/06**

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CPC (source: EP KR US)

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